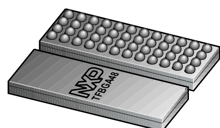


SOT1365-1

Plastic thin fine-pitch ball grid array package; 48 balls, 0.65 mm pitch, 3 mm x 8 mm x 1.05 mm body

10 November 2017 — Package information

1. Package summary

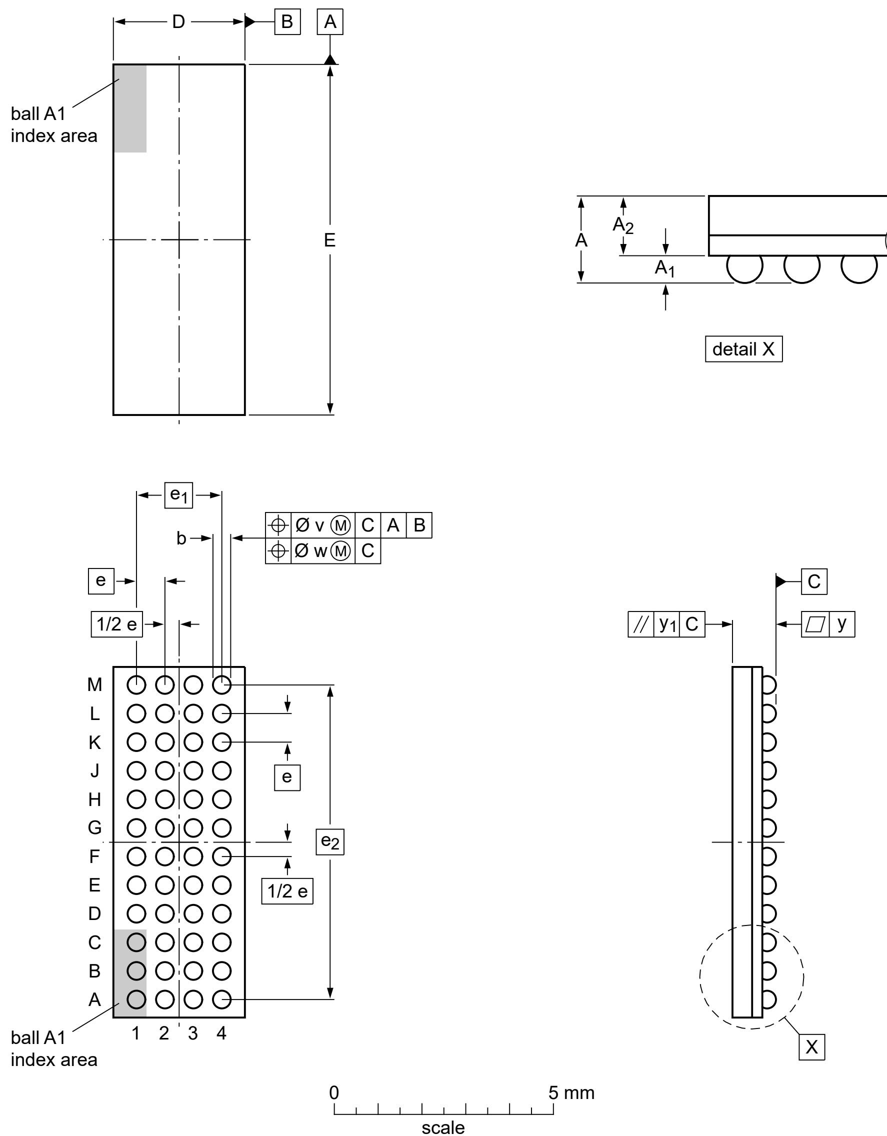
Terminal position code	B (bottom)
Package type descriptive code	TFBGA48
Package type industry code	TFBGA48
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-8-2014
Manufacturer package code	SOT1365-1

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		7.9	-	8	8.1	mm
A	seated height		-	-	-	1.05	mm
A_2	package height		0.63	-	0.68	0.73	mm
e	nominal pitch		-	-	0.65	-	mm
n_2	actual quantity of termination		-	-	48	-	A/A

2. Package outline

TFBGA48: plastic low profile fine-pitch ball grid array package; 48 balls **SOT1365-1**



Dimensions

Unit		A	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y	y_1
	max	1.05	0.35	0.73	0.45	3.1	8.1							
mm	nom	0.98	0.30	0.68	0.40	3.0	8.0	0.65	1.95	7.15	0.15	0.05	0.08	0.1
	min	0.88	0.25	0.63	0.35	2.9	7.9							

sot1365-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1365-1	- - -	- - -	- - -			~~14-01-03~~ 14-08-12

Fig. 1. Package outline TFBGA48 (SOT1365-1)

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3. Soldering

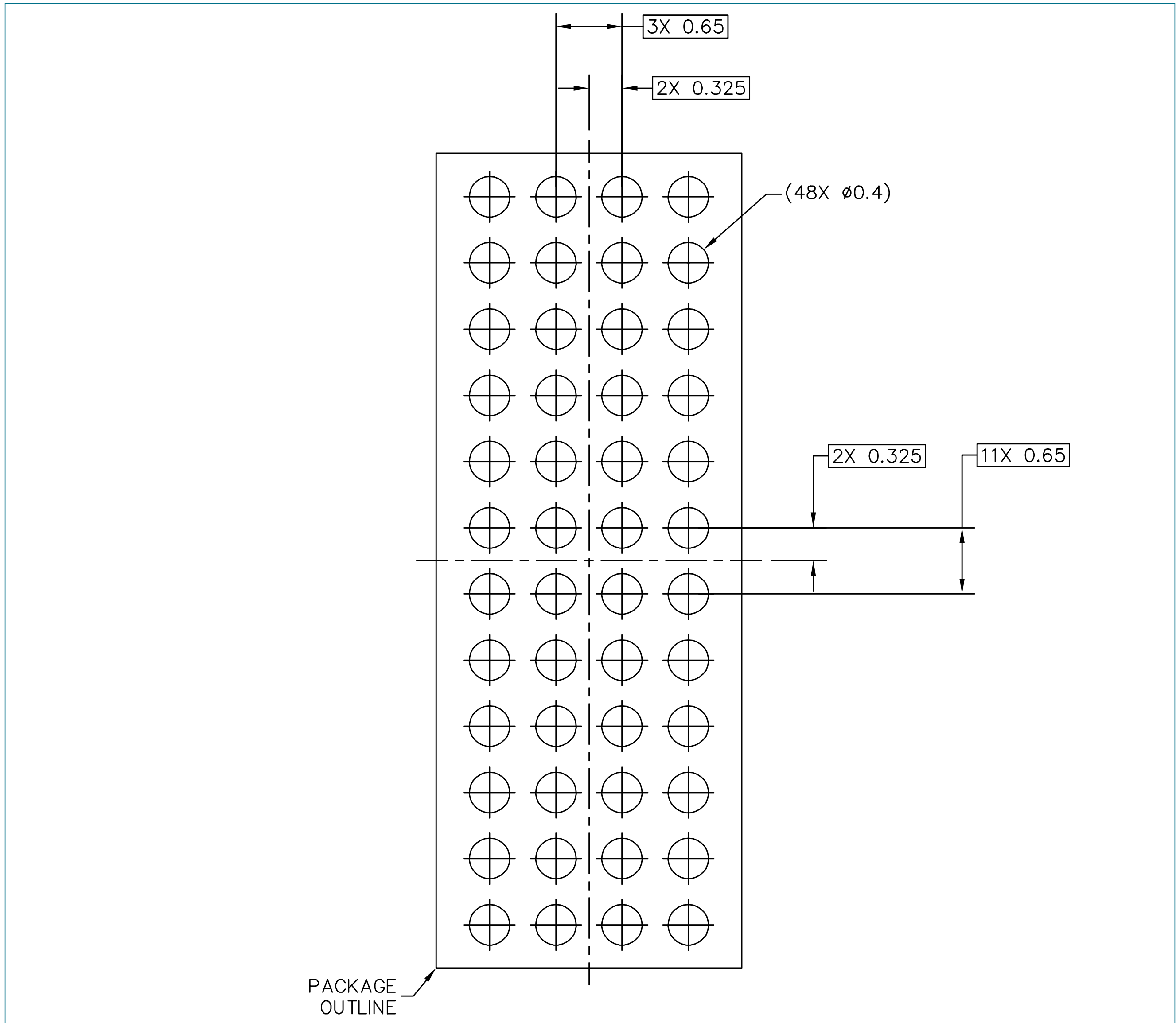

Fig. 2. Reflow soldering footprint for TFBGA48 (SOT1365-1)

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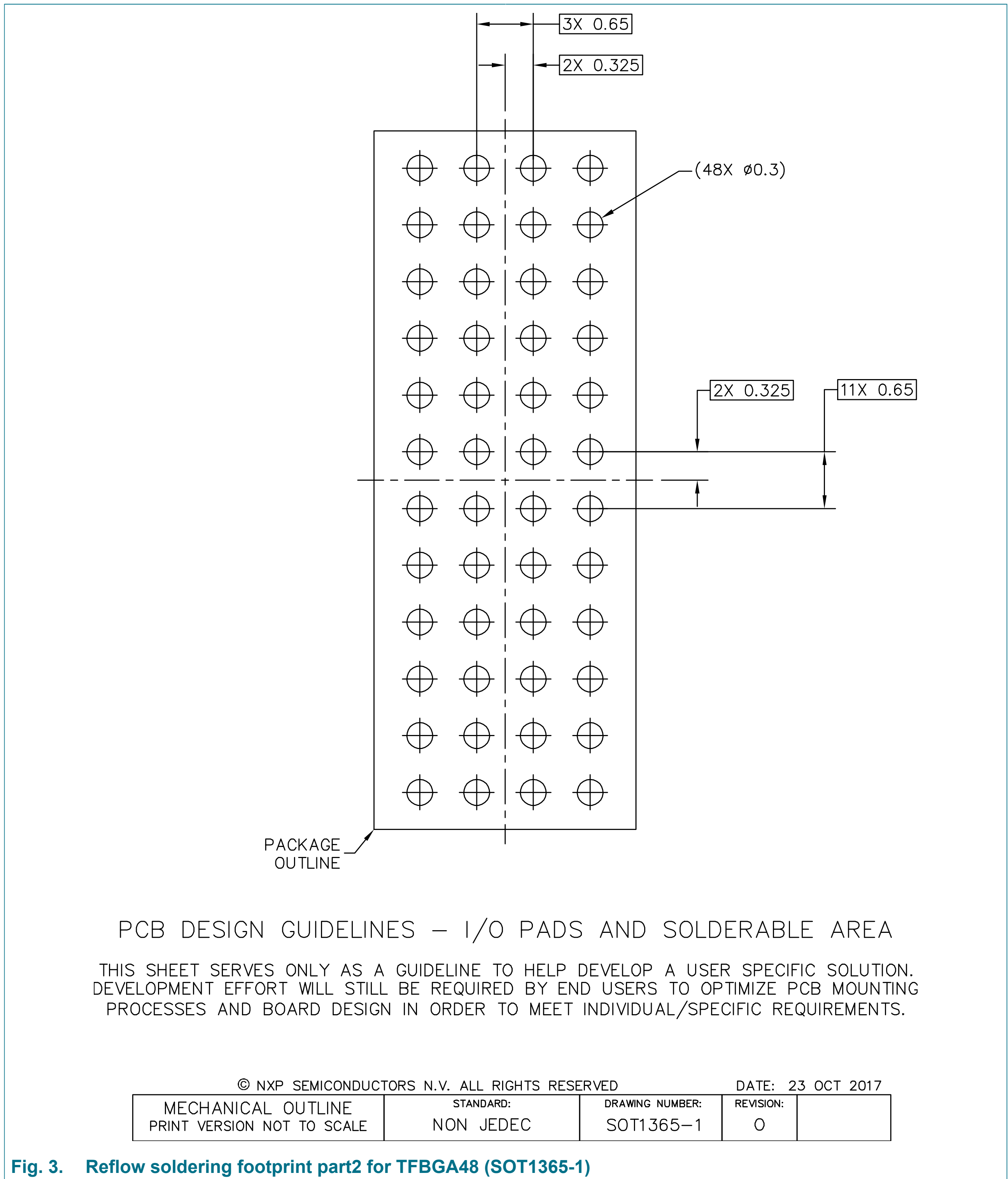

Fig. 3. Reflow soldering footprint part2 for TFBGA48 (SOT1365-1)

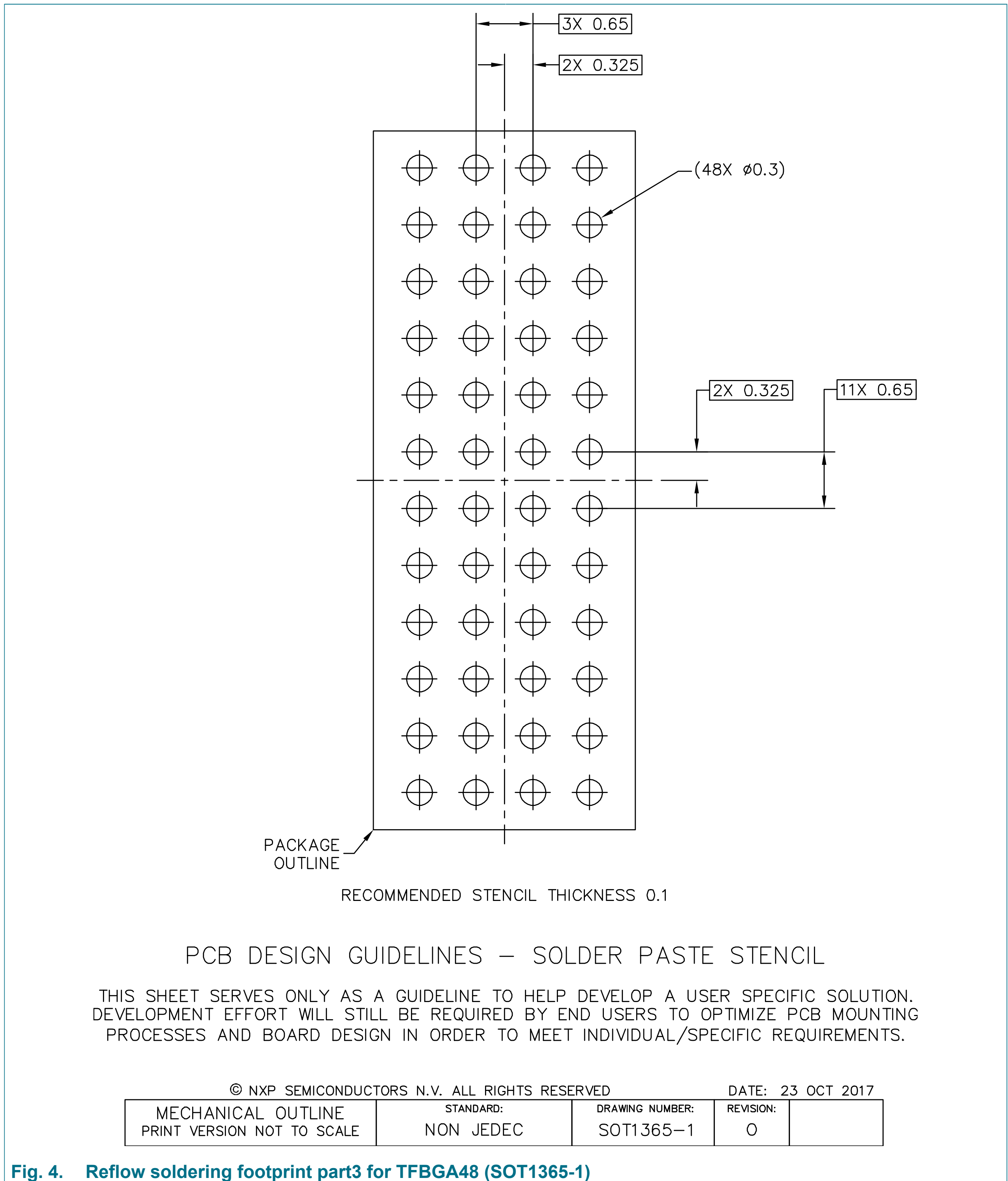

Fig. 4. Reflow soldering footprint part3 for TFBGA48 (SOT1365-1)

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5. Contents

1. Package summary.. 1
2. Package outline... 2
3. Soldering... 3
4. Legal information... 6

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